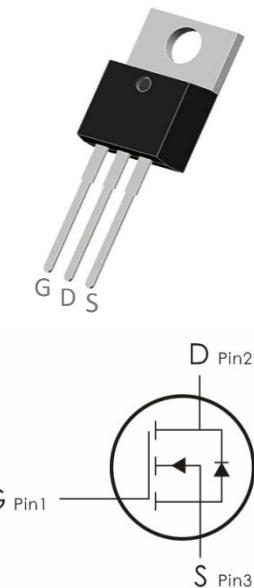


## Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent  $R_{DS(on)}$  with low gate charge. It can be used in a wide variety of applications.



## Features:

- 1)  $V_{DS}=100V, I_D=15A, R_{DS(on)}<90m\Omega @ V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low  $R_{DS(on)}$ .
- 5) Excellent package for good heat dissipation.

## Absolute Maximum Ratings: ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current-T <sub>c</sub> =25°C <sup>3</sup>	15	A
	Continuous Drain Current-T <sub>c</sub> =100°C	12	
$P_D$	Power Dissipation-T <sub>C</sub> =25°C	59	W
$E_{AS}$	Single pulse avalanche energy <sup>5</sup>	6.1	mJ
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55-+150	°C

## Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{eJC}$	Thermal Resistance,Junction to Case	2.1	°C/W
$R_{eJA}$	Thermal Resistance,Junction to Ambient	62	°C/W

## Package Marking and Ordering Information:

Part NO.	Marking	Package
15N10	15N10	TO-220

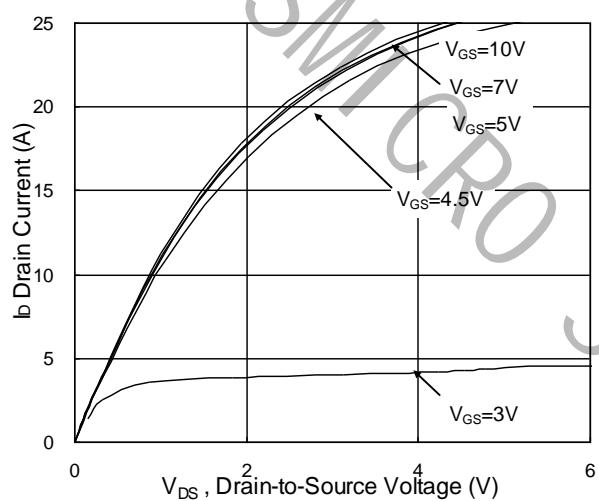
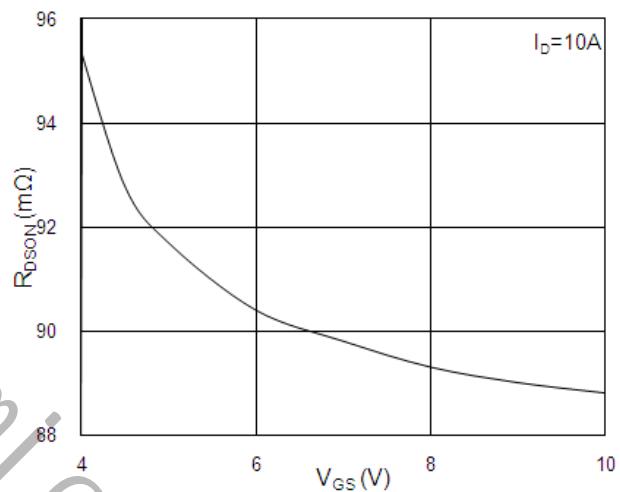
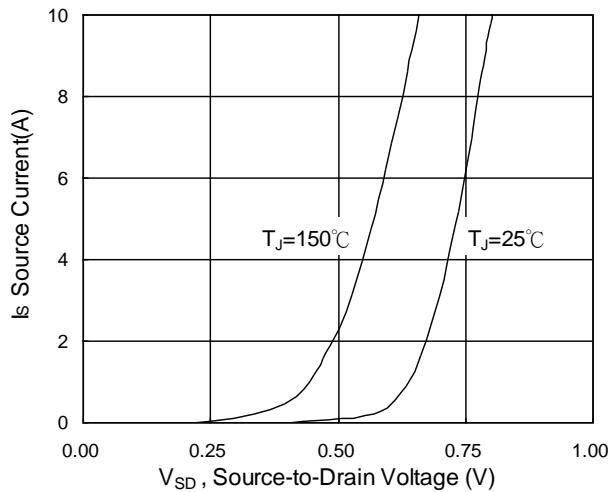
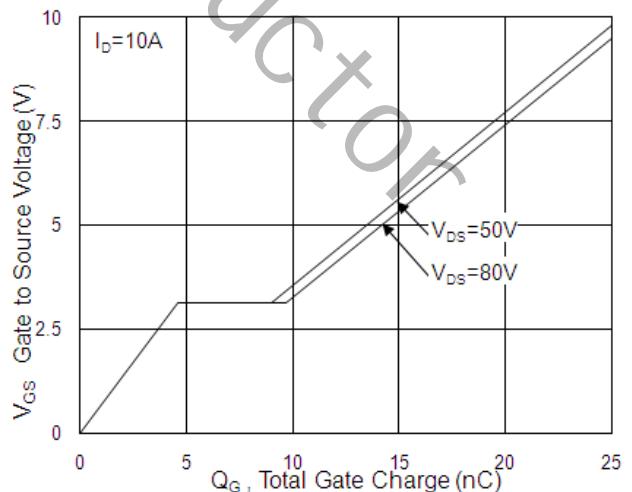
## Electrical Characteristics: ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	100	---	---	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}$	---	---	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	1.5	---	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance <sup>1</sup>	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}$	---	67	90	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance <sup>2</sup>	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	1535	---	pF
$C_{\text{oss}}$	Output Capacitance <sup>2</sup>		---	60	--	
$C_{\text{rss}}$	Reverse Transfer Capacitance <sup>2</sup>		---	37	---	
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=10\text{A}$ $R_{\text{G}}=3.3 \Omega$	---	4.2	---	ns
$t_r$	Rise Time		---	8.2	---	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	35.6	---	ns
$t_f$	Fall Time		---	9.6	---	ns
$Q_g$	Total Gate Charge	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=80\text{V}, I_{\text{D}}=10\text{A}$	---	26.2	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	4.6	---	nC
$Q_{\text{gd}}$	Gate-Drain "Miller" Charge		---	5.1	---	nC
<b>Drain-Source Diode Characteristics</b>						
$I_s$	$V_G=V_D=0\text{V}$ <sup>3</sup>		---	---	15	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=1\text{A}$	---	---	1.2	V
$\text{Tr}_r$	Reverse Recovery Time	$I_f=10\text{A}, V_{\text{GS}}=0\text{V}$	---	37	---	NS

Qrr	Reverse Recovery Charge	dI/dt=100A/us	---	27.3	---	NC
-----	-------------------------	---------------	-----	------	-----	----

**Notes:**

- 1: Pulse test; pulse width  $\leq$  300us, duty cycle  $\leq$  2%.
- 2: Guaranteed by design, not subject to production testing.
- 3: Package limitation current is 10A.
- 4: Repetitive rating, pulse width limited by max junction temperature.
- 5: Starting TJ = 25°C, L = 0.1mH, IAS = 11A.

**Typical Characteristics:** (T<sub>c</sub>=25°C unless otherwise noted)

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs G-S Voltage**

**Fig.3 Source Drain Forward Characteristics**

**Fig.4 Gate-Charge Characteristics**

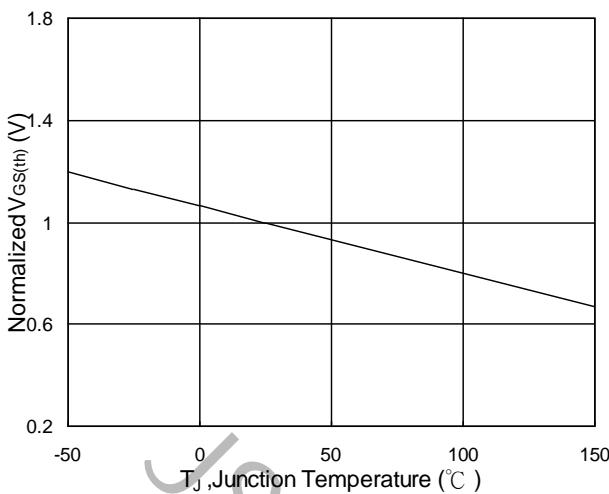
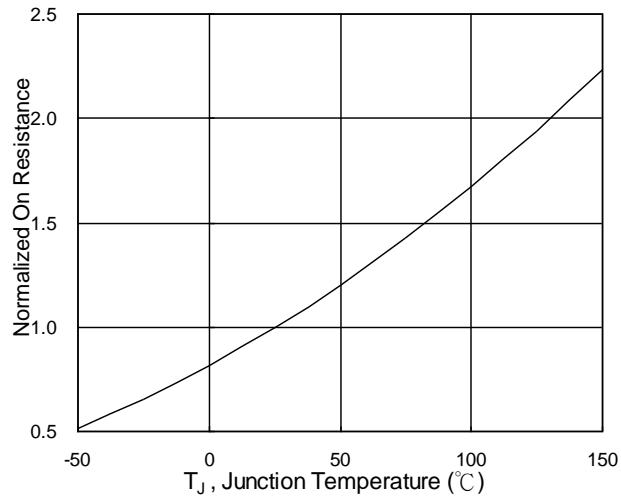
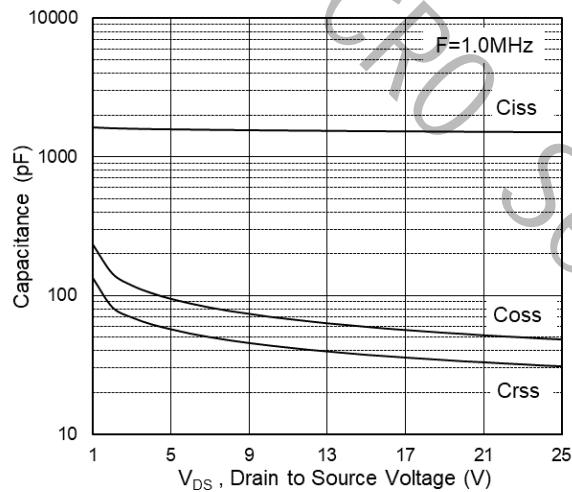

 Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$ 

 Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$ 


Fig.7 Capacitance

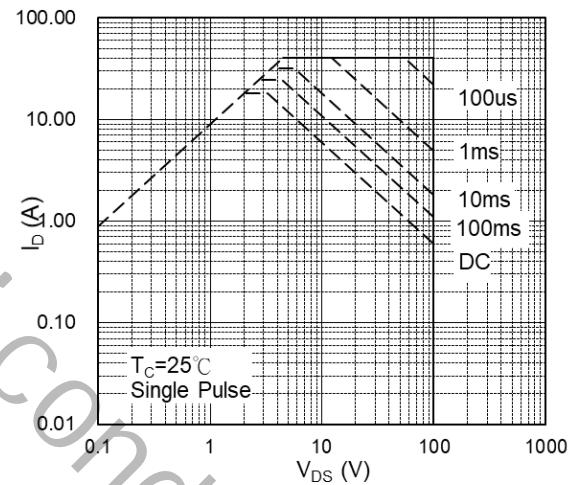


Fig.8 Safe Operating Area

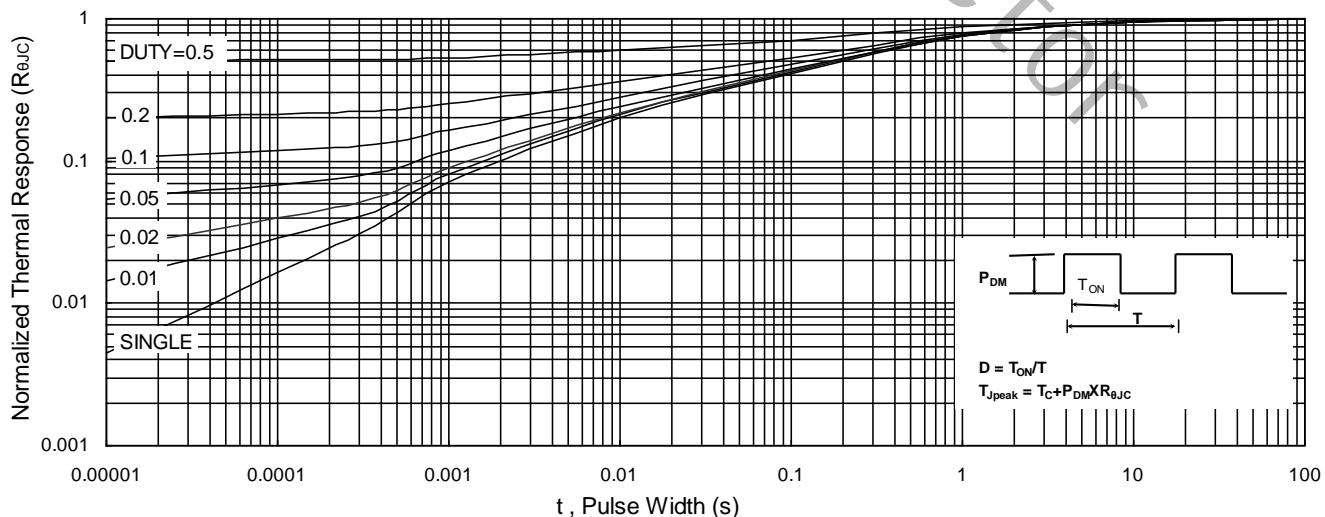


Fig.9 Normalized Maximum Transient Thermal Impedance

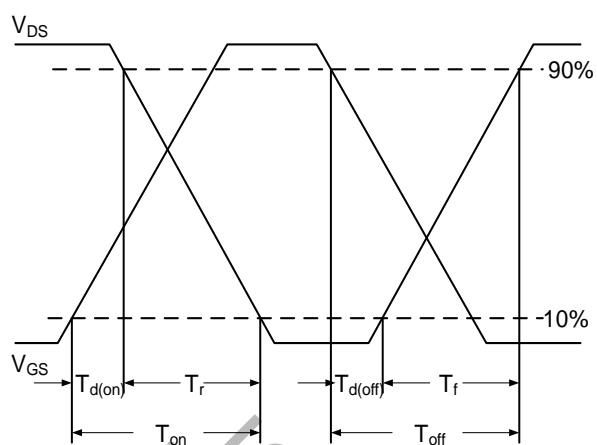


Fig.10 Switching Time Waveform

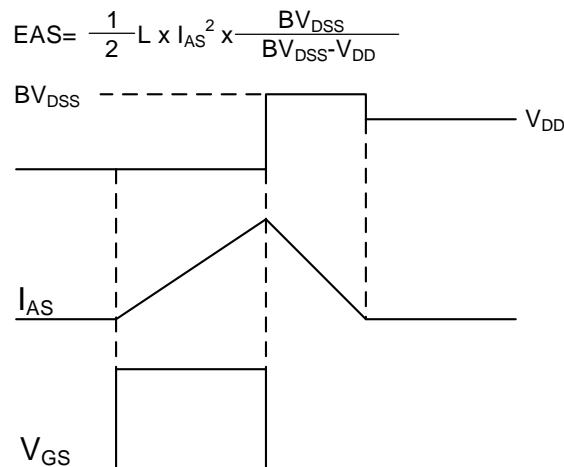


Fig.11 Unclamped Inductive Switching Waveform